

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>In re application of:</b> Tien-Jen Cheng, et al.	<b>Dated:</b> December 11, 2006
<b>Serial Number:</b> 10/604,578	<b>Examiner:</b> Nathan W. Ha
<b>Filing date:</b> July 31, 2003	<b>Group Art Unit:</b> 2814 <b>CONF. No.:</b> 1577
<b>Title:</b> Encapsulated Pin Structure for Improved Reliability of Wafer	IBM Corporation D/18G, B/321, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

**AMENDMENT UNDER 37 C.F.R. § 1.116**

Hon. Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

Sir:

In response to the Final Office Action dated **October 11, 2006**, Applicant respectfully request reconsideration and allowance of the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of Claims beginning on page 2 of this paper.

**Remarks** begin on page 6 of this paper.